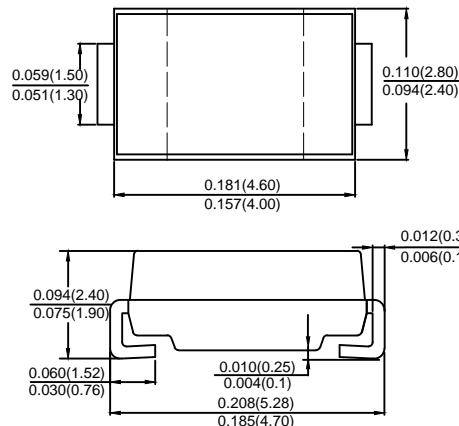


**S2A-S2M****Surface Mount Standard Rectifiers**

Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

SMA/DO-214AC



Mechanical Date

- **Case:** JEDEC DO-214AC (SMA) molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Maximum Ratings & Thermal Characteristics

Rating at 25°C ambient temperature unless otherwise specified

Single phase,half wave,60Hz,resistive or inductive load

For capacitive load derate current by 20%

Type Number	SYMBOL	S2A	S2B	S2D	S2G	S2J	S2K	S2M	Unit
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Average Rectified Output Current @T _L =100 °C	IF(AV)					2.0			A
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}					50			A
Rating for fusing (t<8.3ms)	I ² t				14.94				A ² s
Forward Voltage @IF=2.0A	V _{FM}			1.0					V
Peak Reverse Current @T _A =25 °C	I _R			5.0					uA
At Rated DC Blocking Voltage @T _A =125 °C				200					
Typical Junction Capacitance (Note 1)	C _J			25					pF
Typical Thermal Resistance Junction to Ambient(Note 2)	R _{θ JA}			65					°C/W
Operating Temperature Range	T _J			-55 to+150					°C
Storage Temperature Range	T _{STG}			-55 to +150					°C

Note: 1. Measured at 1.0 MHz and Applied reverse Voltage of 4.0V D.C

2.Thermal Resistance from Junction to Ambient at 0.375(9.5mm) lead length .



S2A-S2M

Surface Mount Standard Rectifiers

Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

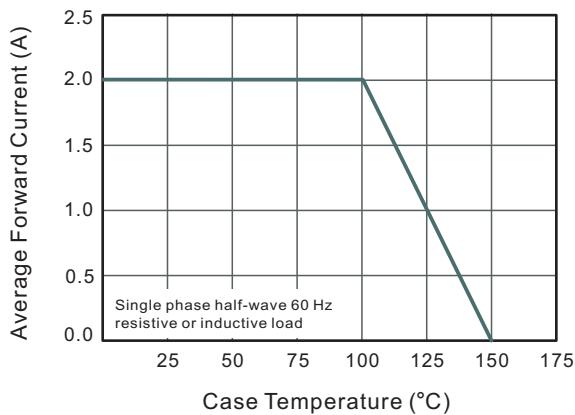


Fig.2 Typical Reverse Characteristics

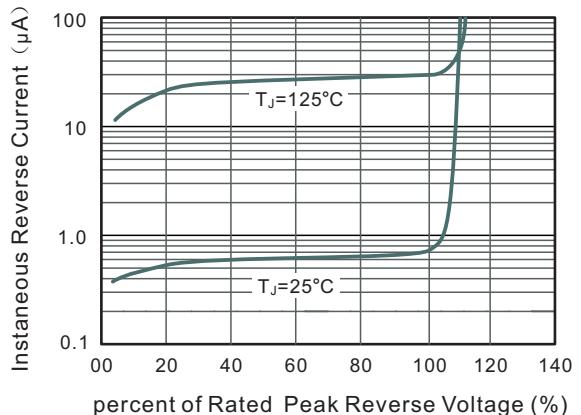


Fig.3 Typical Forward Characteristic

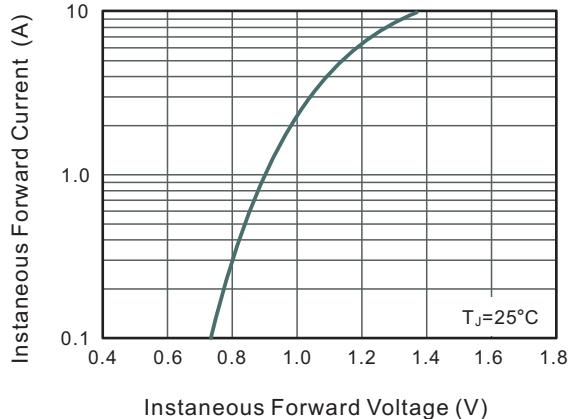


Fig.4 Typical Junction Capacitance

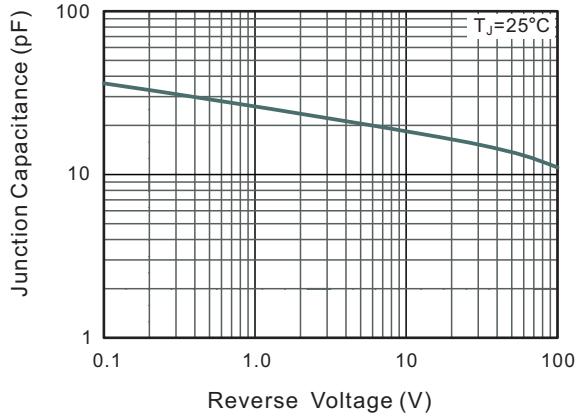
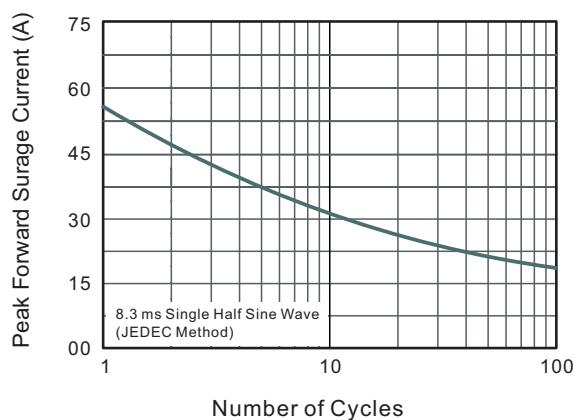


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



SMA PAD LAYOUT

